

Latch-Up Performance Exceeds 250 mA Per

Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)

- 2000-V Human-Body Model (A114-A)

- 1000-V Charged-Device Model (C101)

>2 V at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C

ESD Protection Exceeds JESD 22

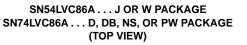
- 200-V Machine Model (A115-A)

JESD 17

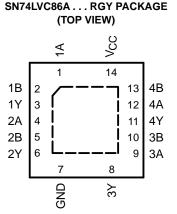
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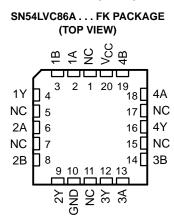
#### FEATURES

- Operate From 1.65 V to 3.6 V
- Specified From –40°C to 85°C, –40°C to 125°C, and –55°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 4.6 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C



	1A [ 1B [ 1Y [ 2A [ 2B [ 2Y [ GND [	1 2 3 4 5 6 7	0	14 13 12 11 10 9 8		V <sub>CC</sub> 4B 4A 4Y 3B 3A 3Y
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NC - No internal connection

### **DESCRIPTION/ORDERING INFORMATION**

The SN54LVC86A quadruple 2-input exclusive-OR gate is designed for 2.7-V to 3.6-V V<sub>CC</sub> operation, and the SN74LVC86A quadruple 2-input exclusive-OR gate is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The 'LVC86A devices perform the Boolean function  $Y = A \oplus B$  or  $Y = \overline{AB} + A\overline{B}$  in positive logic.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PA	PACKAGE <sup>(1)</sup> ORDERABLE PART NUMBER		TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	- RGY Reel of 1000 SN74LVC86ARGYR		LC86A
		Tube of 50	SN74LVC86AD	
	SOIC – D	Reel of 2500	SN74LVC86ADR	LVC86A
		Reel of 250	SN74LVC86ADT	
	SOP – NS	Reel of 2000	SN74LVC86ANSR	LVC86A
–40°C to 125°C	SSOP – DB	Reel of 2000	SN74LVC86ADBR	LC86A
		Tube of 90	SN74LVC86APW	
	TSSOP – PW	Reel of 2000	SN74LVC86APWR	LC86A
		Reel of 250	SN74LVC86APWT	
	CDIP – J	Tube of 25	SNJ54LVC86AJ	SNJ54LVC86AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LVC86AW	SNJ54LVC86AW
	LCCC – FK	Tube of 55	SNJ54LVC86AFK	SNJ54LVC86AFK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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Copyright © 1993–2005, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

## SN54LVC86A, SN74LVC86A QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES



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## **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

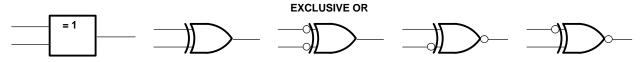
Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

#### FUNCTION TABLE (EACH GATE)

INP	UTS	OUTPUT				
Α	В	Y				
L	L	L				
L	Н	Н				
н	L	Н				
Н	Н	L				

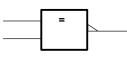
#### EXCLUSIVE-OR LOGIC

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



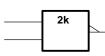
These five equivalent exclusive-OR symbols are valid for an SN74LVC86A gate in positive logic; negation may be shown at any two ports.

#### LOGIC-IDENTITY ELEMENT



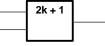
The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

#### **EVEN-PARITY ELEMENT**



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

#### **ODD-PARITY ELEMENT**



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

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### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	6.5	V
VI	Input voltage range <sup>(2)</sup>		-0.5	6.5	V
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>0</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current			±50	mA
	Continuous current through $V_{CC}$ or GND			±100	mA
		D package <sup>(4)</sup>		86	
		DB package <sup>(4)</sup>		96	
$\theta_{JA}$	Package thermal impedance	NS package <sup>(4)</sup>		76	°C/W
		PW package <sup>(4)</sup>		113	
		RGY package <sup>(4)</sup>		47	
T <sub>stg</sub>	Storage temperature range	· · · · · ·	-65	150	°C
P <sub>tot</sub>	Power dissipation	$T_A = -40^{\circ}C$ to $125^{\circ}C^{(5)(6)}$		500	mW

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of  $V_{CC}$  is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

(5) For the D package: above 70°C, the value of P<sub>tot</sub> derates linearly with 8 mW/K.

(6) For the DB, DGV, NS, and PW packages: above 60°C, the value of P<sub>tot</sub> derates linearly with 5.5 mW/K.

### **Recommended Operating Conditions**<sup>(1)</sup>

			SN54LV	C86A		
			–55 TO <sup>2</sup>	125°C	UNIT	
			MIN	MAX		
V	Supply veltage	Operating	2	3.6	V	
V <sub>CC</sub>	Supply voltage	Data retention only	1.5		v	
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		V	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	V	
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 2.7 V		-12	~ ^	
IOH	High-level output current	$V_{CC} = 3 V$		-24	4 mA	
	Level and a david an investig	V <sub>CC</sub> = 2.7 V		12		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V		24	mA	
$\Delta t / \Delta v$	Input transition rise or fall rate	·		9	ns/V	

 All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# SN54LVC86A, SN74LVC86A QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

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# **Recommended Operating Conditions**<sup>(1)</sup>

					SN74L	VC86A				
			T <sub>A</sub> = 25	T <sub>A</sub> = 25°C		D 85°C	–40 TO	125°C	UNIT	
			MIN	MAX	MIN	МАХ	MIN	MAX		
V	Cupply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V	
V <sub>CC</sub>	Supply voltage	Data retention only	1.5		1.5		1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65  imes V_{CC}$		$0.65 \times V_{\text{CC}}$		$0.65 \times V_{CC}$			
VIH	High-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V	1.7		1.7		1.7		V	
	Voltago	$V_{CC}$ = 2.7 V to 3.6 V	2		2		2			
		V <sub>CC</sub> = 1.65 V to 1.95 V	0	$.35 \times V_{CC}$		$0.35 \times V_{CC}$		$0.35 \times V_{CC}$		
V <sub>IL</sub> Low-leve voltage	Low-level input	$V_{CC}$ = 2.3 V to 2.7 V		0.7		0.7		0.7	V	
	vollago	$V_{CC}$ = 2.7 V to 3.6 V		0.8		0.8		0.8		
VI	Input voltage		0	5.5	0	5.5	0	5.5	V	
Vo	Output voltage		0	V <sub>CC</sub>	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 1.65 V		-4		-4		-4		
	High-level	V <sub>CC</sub> = 2.3 V		-8		-8		-8	mA	
I <sub>OH</sub>	output current	V <sub>CC</sub> = 2.7 V		-12		-12		-12	ШA	
		$V_{CC} = 3 V$		-24		-24		-24		
		V <sub>CC</sub> = 1.65 V		4		4		4		
	Low-level output	V <sub>CC</sub> = 2.3 V	8			8		8	٣٨	
I <sub>OL</sub>	current	V <sub>CC</sub> = 2.7 V		12		12		12	mA	
		$V_{CC} = 3 V$		24		24		24	L	
$\Delta t / \Delta v$	Input transition ris	se or fall rate		9		9		9	ns/V	

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### **Electrical Characteristics**

over operating free-air temperature range (unless otherwise noted)

			SN54L			
PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	–55 TC	UNIT		
				MIN	TYP MAX	
	I <sub>OH</sub> = -100 μA		2.7 V to 3.6 V	V <sub>CC</sub> – 0.2		
N/	40 40	2.7 V	2.2			
V <sub>OH</sub>	$I_{OH} = -12 \text{ mA}$	3 V	2.4		V	
	$I_{OH} = -24 \text{ mA}$		3 V	2.2		
	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V		0.2		
V <sub>OL</sub>	I <sub>OL</sub> = 12 mA		2.7 V		0.4	V
	I <sub>OL</sub> = 24 mA		3 V		0.55	
l <sub>l</sub>	$V_{I} = 5.5 \text{ V or GND}$		3.6 V		±5	μA
I <sub>CC</sub>	$V_{I} = V_{CC} \text{ or } GND$	$I_{O} = 0$	3.6 V		10	μA
Δl <sub>CC</sub>	One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND		2.7 V to 3.6 V		500	μΑ
C <sub>i</sub>	$V_{I} = V_{CC} \text{ or } GND$		3.3 V		5 <sup>(1)</sup>	pF

(1)  $T_A = 25^{\circ}C$ 

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### **Electrical Characteristics**

over operating free-air temperature range (unless otherwise noted)

						;	SN74LVC86	Α			
PARAMETER	TEST CONDITIONS		V <sub>cc</sub>	T <sub>A</sub> = 25°C			–40 TO 85°C		–40 TO 125°C		UNIT
				MIN	TYP M	MAX	MIN	MAX	MIN	MAX	1
	I <sub>OH</sub> = −100 μA		1.65 V to 3.6 V	V <sub>CC</sub> – 0.2			$V_{CC} - 0.2$		$V_{CC} - 0.3$		
	$I_{OH} = -4 \text{ mA}$		1.65 V	1.29			1.2		1.05		1
V	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			1.7		1.55		V	
V <sub>OH</sub>	L _ 12 mA		2.7 V	2.2			2.2		2.05		v
	I <sub>OH</sub> = -12 mA	3 V	2.4			2.4		2.25			
	I <sub>OH</sub> = -24 mA	3 V	2.3			2.2		2		1	
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.1		0.2		0.3		
	$I_{OL} = 4 \text{ mA}$	1.65 V		(	0.24		0.45		0.6	1	
V <sub>OL</sub>	I <sub>OL</sub> = 8 mA		2.3 V			0.3		0.7		0.75	V
	I <sub>OL</sub> = 12 mA		2.7 V			0.4		0.4		0.6	1
	I <sub>OL</sub> = 24 mA		3 V		(	0.55		0.55		0.8	1
lı lı	$V_{I} = 5.5 V \text{ or GND}$		3.6 V			±1		±5		±20	μΑ
I <sub>CC</sub>	$V_{I} = V_{CC}$ or GND	$I_0 = 0$	3.6 V			1		10		40	μΑ
ΔI <sub>CC</sub>	One input at $V_{CC} - 0.6$ V Other inputs at $V_{CC}$ or G		2.7 V to 3.6 V			500		500		5000	μA
Ci	$V_I = V_{CC}$ or GND		3.3 V		5						pF

## **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>cc</sub>	SN54LV 55 TO		UNIT
				MIN	MAX	
	•	Y	2.7 V		5.6	20
<sup>L</sup> pd	A	Ť	$3.3~\textrm{V}\pm0.3~\textrm{V}$	1	4.6	ns

### **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

	FROM					SN	74LVC86	6A			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>cc</sub>	T,	<sub>A</sub> = 25°C		-40 TO	85°C	-40 TO	125°C	UNIT
	(	(001101)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			$1.8 \text{ V} \pm 0.15 \text{ V}$	1	4.1	9.4	1	9.9	1	11.4	
	•	v	$2.5~V\pm0.2~V$	1	2.9	7.1	1	7.6	1	9.7	~~
t <sub>pd</sub>	A	Y	2.7 V	1	2.8	5.4	1	5.6	1	7.1	ns
			$3.3~\textrm{V}\pm0.3~\textrm{V}$	1	2.5	4.4	1	4.6	1	5.8	
t <sub>sk(o)</sub>			$3.3~V\pm0.3~V$					1		1.5	ns

## **Operating Characteristics**

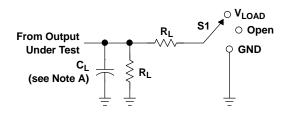
 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	v <sub>cc</sub>	ТҮР	UNIT
			1.8 V	6.5	
C <sub>pd</sub>	Power dissipation capacitance per gate	f = 10 MHz	2.5 V	7.5	pF
			3.3 V	8.5	

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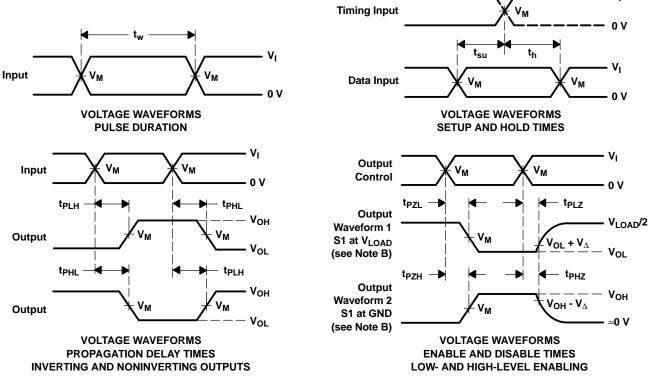
#### PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

	INPUTS				•	_	
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	RL	$V_{\Delta}$
1.8 V $\pm$ 0.15 V	V <sub>CC</sub>	≤ <b>2</b> ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	30 pF	<b>500</b> Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>0</sub> = 50  $\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

#### Figure 1. Load Circuit and Voltage Waveforms

6-Dec-2006



## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9761901Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9761901QCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9761901QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN74LVC86AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LVC86ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ADTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LVC86APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC86ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LVC86ARGYRG4	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

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Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ54LVC86AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LVC86AJ	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LVC86AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



MLCC006B - OCTOBER 1996

### FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



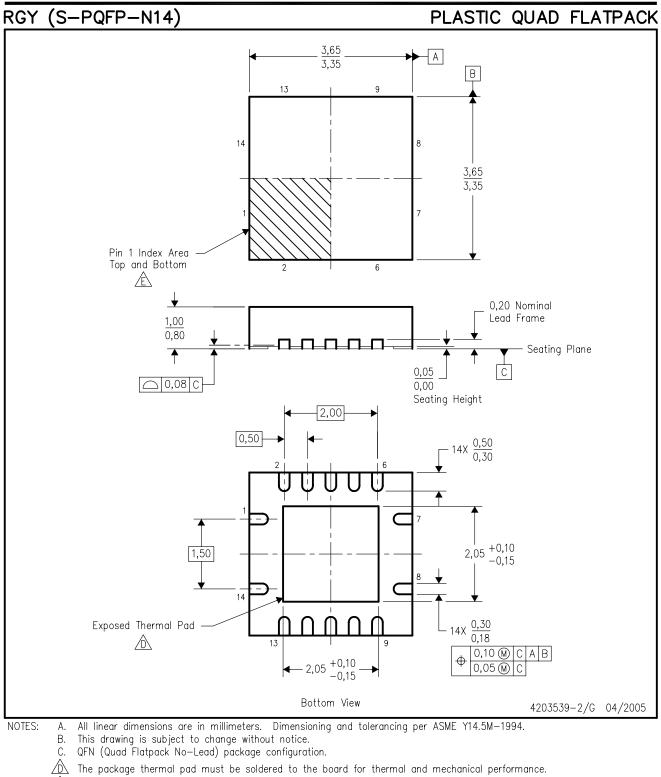
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.





È Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

F. Package complies to JEDEC MO-241 variation BA.



### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

## DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

# PW (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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